mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SSRDC Series

DC Load Solid State Relay Hockey Puck

File E29244

Users should thoroughly review the technical data before selecting a product part number. It is recommended that users also seek out the pertinent approvals files of the agencies/laboratories and review them to ensure the product meets the requirements for a given application.

Features

- Standard "hockey puck" package.
- LED indicator.
- 12, 25 & 40A versions.
- 200V DC output types.
- DC input and output versions.
- 1500V DC optical isolation.
- Cover design with anti-rotation barriers

Engineering Data

Form: 1 Form A (SPST-NO). Duty: Continuous. Isolation: 1500V DC minimum. Temperature Range: Storage: -30°C to +100°C Operating: -30°C to +80°C. Case Material: Plastic, UL rated 94V-0. Case and Mounting: Refer to outline dimension. Termination: Refer to outline dimension. Termination: Refer to outline dimension. Approximate Weight: For 12A : 4.09 oz. (116g). For 25A & 40A : 5.11 oz. (145g).

Ordering Information						
	Typical Part Number	SSRDC	-200	D	25	
1. Basic Series: SSRDC = DC Load hockey puck solid state relay						
2. Line Voltage: 200VDC						
3. Input Type & Voltage: D = 3.5 -	32VDC					
4. Maximum Switching Rating:	12 = 12A, mounted to heatsink 25 = 25A, mounted to heatsink 40 = 40A, mounted to heatsink				-	

Our authorized distributors are more likely to maintain the following items in stock for immediate delivery.

SSRDC-200D12 SSRDC-200D25 SSRDC-200D40

Input Specifications

Parameter	Units	SSRDC-200D12 SSRDC-200D25 SSRDC-200D40				
Control Voltage Range VIN	VDC	3.5 - 32				
Must Operate Voltage VIN(OP) (Min.)	VDC	3.5				
Must release Voltage VIN(REL) (Min.)	VDC	1				
Input Current (Max.)	mA	30				

1

Datasheets and product specification according to IEC 61810-1 and to be used only together with the 'Definitions' section. Datasheets and product data is subject to the terms of the disclaimer and all chapters of the 'Definitions' section, available at <u>http://relays.te.com/definitions</u> Datasheets, product data, 'Definitions' section, application notes and all specifications are subject to change.

SSRDC Series (Continued)

Output Specifications (@ 25° C, unless otherwise specified)

Parameter	Units	12A Models	25A Models	40A Models
Load Voltage Range V∟	VDC	200	200	200
Load Current Range I⊥ *	А	12	25	40
Single Cycle Surge Current	А	120	120	200
Leakage Current (Off-State) @Rated Current	mA	12	12	12
On-State Voltage Drop @Rated Current	VDC	2.83	2.83	2.83
Turn-On Time (Max.)	μs	600	600	600
Turn-Off Time (Max.)	μs	2600	2600	2600
Thermal Resistance, Junction to Case	°C/W	0.7	0.7	0.5

* See Derating curve

Electrical Characteristics (Thermal Derating Curves)



Heatsink Recommendations

- We recommend that solid state relay modules be mounted to a heatsink sufficient to maintain the module's base temperature at less than 85°C under worst case ambient temperature and load conditions.
- The heatsink mounting surface should be a smooth (30-40 micro-inch finish), flat (30-40 micro-inch flatness across mating area), un-painted surface which is clean and free of oxidation.
- An even coating of thermal compound (Dow Corning DC340 or equivalent) should be applied to both the heatsink and module
- The module should be mounted to the heatsink using two #8 screws.

Operating Diagrams



Outline Dimensions



* Overall height dimensions includes with clear cover Dimensions in mm

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2